

# 工程變更客戶通知單 Engineering Change Customer Notification

ECR/ECN 單號: ECR/ECN Number:	EO000264
日期: Date:	2024/08/12
變更者/郵箱: Author/Mail	Paul Liu
客戶端工程變更需求確認: (signature) EC request confirmation by customer	請於 10 工作日內簽回,若超過 10 日未簽回將視為同意此變更 Please sign back within 10 working days, if you do not sign back within 10 working days, you will be deemed to agree to this change.
客戶端工程變更完成確認 : (signature) EC completion confirmation by customer	請於 10 工作日內簽回,若超過 10 日未簽回將視為已確認 Please sign back within 10 working days. if you do not sign back within 10 working days, it will be deemed as confirmed.

## 1.影響產品 Affected Products

1. 粉音性的 AIICCICU I TOUUCIS		
產品類別	零件編號	
Product Category	Part Number	
	RECE.20279.001E.01	
	RECE.20369.001E.01	
	RECE.20449.001E.01	



# 2.變更訊息 Information of change

	□工程設計變更	□生產製程變更			
變更類型	Engineering Design Ch	ange Production Process improvement			
Type of Change	■其他:				
	Packaging change				
	Correct moisture sensitiv	e level from MSL3 to MSL2.			
變更原因					
Reason for change					
變更說明	Change moisture sensitive label from MSL3 to MSL2 in the packaging.				
发文机仍 Description of Change					
Description of change					
變更影響 Impact of change	□外觀 Appearance	□功能 Function □規格 Specification			
	□ 品質 Quality	□可靠度 Reliability □法規 Regulations			
	■包裝 Package:	□ 其他 Others:			
	■ O A Tuckage.				
	上述影響描述:	Not impact function.			
	Describe if above	Change moisture sensitive label from MSL3 to			
	applies: Yes	MSL2 in the packaging.			
	appliest les				
預估轉換日期 Forecast Estimated Transition Date	Last buy (old product)	N/A			
	New buy (new product)	Immediately change			

3.計劃表 Schedule

N/A

4.變更圖例 Illustration of Change 變更前/Before





#### Caution

This bag contains
MOISTURE-SENSITIVE DEVICES



If blank, see adjacent

1.	Calculated shelf life in sealed bag: 12 months at <40°C and	d
	<90% relative humidity (RH)	

2. Peak package body temperature:  $\frac{260}{\text{lf blank, see adjacent bar code label}} ^{\circ}\text{C}$ 

- After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
  - a) Mounted within: 168 hours of factory conditions follows: 150 hours of factory conditions ≤30°C/60% RH, or
  - b) Stored per J-STD-033
- 4. Devices require bake, before mounting, if:
  - a) Humidity Indicator Card reads >10% for level 2a 5a devices or >60% for level 2 devices when read at 23 ± 5°C
  - b) 3a or 3b are not met
- If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date:	уууу /	mm /	dd

If blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

### 變更後/After



#### Caution

This bag contains
MOISTURE-SENSITIVE DEVICES



- Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)</li>
- 2. Peak package body temperature:  $\frac{260}{\text{lf blank, see adjacent bar code label}} ^{\circ}\text{C}$
- After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
  - a) Mounted within: 1 year hours of factory conditions

    if blank, see adjacent bar code label

    ≤30°C/60% RH, or
  - b) Stored per J-STD-033
- 4. Devices require bake, before mounting, if:
  - a) Humidity Indicator Card reads >10% for level 2a 5a devices or >60% for level 2 devices when read at 23  $\pm$  5°C
  - b) 3a or 3b are not met
- 5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date: yyyy / mm / dd

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

3/3 R-08-036-B